## **MA2ZD18**

### Silicon epitaxial planar type

For super high speed switching

#### ■ Features

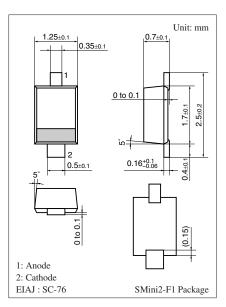
• Low forward voltage V<sub>F</sub>

#### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Reverse voltage	$V_R$	20	V
Repetitive peak reverse voltage	V <sub>RRM</sub>	25	V
Forward current (Average) *1	I <sub>F(AV)</sub>	500	mA
Non-repetitive peak forward surge current *2	I <sub>FSM</sub>	2	A
Junction temperature	T <sub>j</sub>	125	°C
Storage temperature	T <sub>stg</sub>	-55 to +125	°C

Note) \*1: Mounted on an alumina PC board

\*2: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)



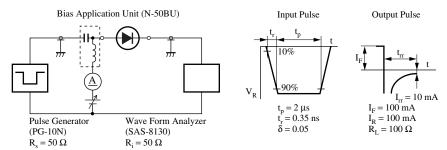
Marking Symbol: 2P

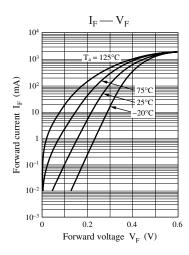
## $\blacksquare$ Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

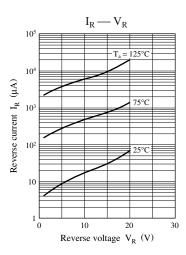
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V <sub>F</sub>	$I_F = 500 \text{ mA}$			0.42	V
Reverse current	$I_R$	$V_R = 20 \text{ V}$			200	μΑ
Terminal capacitance	C <sub>t</sub>	$V_R = 0 V, f = 1 MHz$		100		pF
Reverse recovery time *	t <sub>rr</sub>	$I_F = I_R = 100 \text{ mA}$		7		ns
		$I_{rr} = 10 \text{ mA}, R_L = 100 \Omega$				

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

- 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
- 3. Absolute frequency of input and output is 250 MHz.
- 4. \*: t<sub>rr</sub> measurement circuit







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